

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Τ _A = +25°C
-60V	$10\Omega @ V_{GS} = -5V$	-180mA

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- General Purpose Interfacing Switch
- Power Management Functions
- Analog Switch

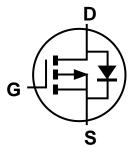
Mechanical Data

- Case: SOT23
- Case Material: UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish (Lead Free Plating).
 Solderable per MIL-STD-202, Method 208 (a)
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)

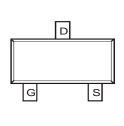








Equivalent Circuit



Top View

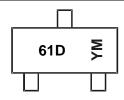
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP610DL-7	SOT23	3,000/Tape & Reel
DMP610DL-13	SOT23	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



61D = Product Type Marking Code
YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)
Y or \(\overline{Y} = Year \) (ex: E = 2017)
M = Month (ex: 9 = September)

Date Code Key

Year	2016		2017	2018		2019	2020		2021	2022		2023
Code	D		Е	F		G	Н		-	J		K
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	-60	V		
Gate-Source Voltage	V_{GSS}	±30	V		
Continuous Drain Current (Note 6) $V_{GS} = -5V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$			I _D	-180 -130	mA
Maximum Continuous Body Diode Forward Currer	t (Note 6)	I _S	-0.5	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1	%)	I _{DM}	-1.2	Α	

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_{D}	310	mW
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	405	°C/W
Total Power Dissipation (Note 6)		P _D	500	mW
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	251	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

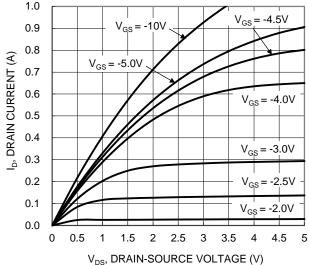
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Cumbal	Min	Tim	May	I Init	Test Condition	
	Symbol	IVIIN	Тур	Max	Unit	lest Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-60	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -60V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	-0.8	_	-2.0	V	$V_{DS} = V_{GS}$, $I_D = -1mA$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	_	10	Ω	$V_{GS} = -5V, I_{D} = -0.1A$	
Forward Transconductance	g FS	_	0.25	_	S	$V_{DS} = -25V, I_D = -0.1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{ISS}	_	24.6	_	pF		
Output Capacitance	Coss	_	4.8	_	pF	$V_{DS} = -25V$, $V_{GS} = 0V$, $f = 1.0MHz$	
Reverse Transfer Capacitance	C _{RSS}	_	2.8	_	pF		
Gate Resistance	R_{G}	_	2,000	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Q_{G}	_	280	_	рC		
Total Gate Charge (V _{GS} = -10V)	Q_G	_	560	_	рC	V _{DS} = -10V, I _D = -100mA	
Gate-Source Charge	Q_{GS}	_	90	_	рС	$V_{DS} = -10V$, $I_D = -100IIIA$	
Gate-Drain Charge	Q_{GD}	_	77	_	рC		
Turn-On Delay Time	t _{D(ON)}	_	2.8		ns		
Turn-On Rise Time	t _R	_	2.6	_	ns	$V_{DD} = -30V, I_D = -0.27A,$	
Turn-Off Delay Time	t _{D(OFF)}	_	11.1	_	ns	$R_{GEN} = 50\Omega$, $V_{GS} = -10V$	
Turn-Off Fall Time	t _F	_	7.2	_	ns	1	

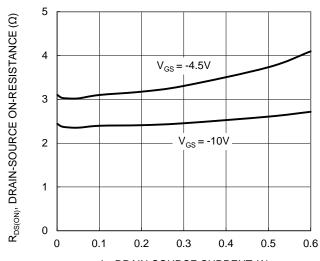
Notes:

- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.





V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 1. Typical Output Characteristic



I_D, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

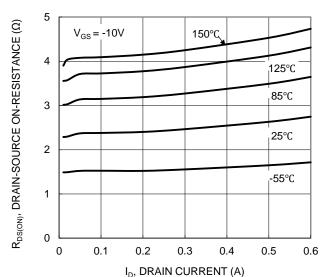


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

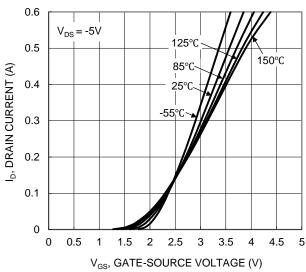


Figure 2. Typical Transfer Characteristic

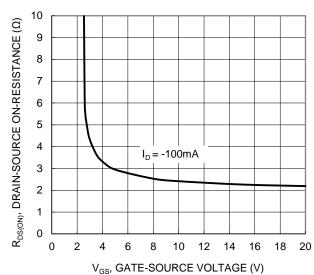
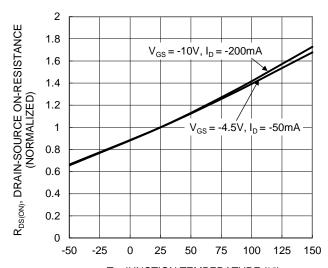


Figure 4. Typical Transfer Characteristic



T_J, JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Temperature



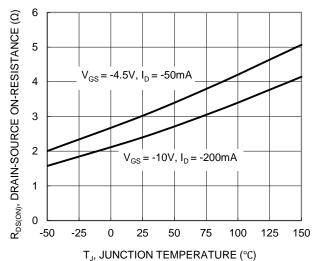
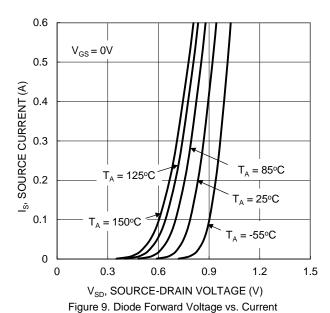


Figure 7. On-Resistance Variation with Temperature



10 9 8 7 $V_{GS}(V)$ 6 5 4 $V_{DS} = -10V, I_{D} = -0.1A$ 3 2 1 0 0.1 0.2 0.3 0.6

 $\label{eq:Qg} \mathbf{Q_g} \mbox{ (nC)}$ Figure 11. Gate Charge

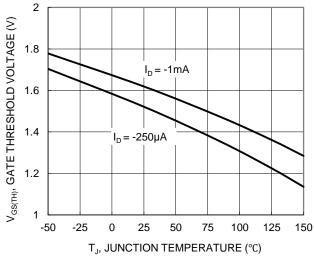


Figure 8. Gate Threshold Variation vs. Junction Temperature

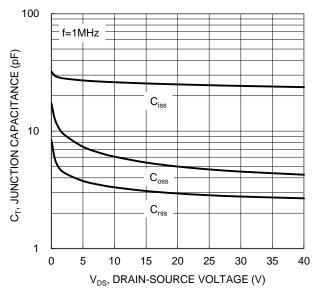


Figure 10. Typical Junction Capacitance



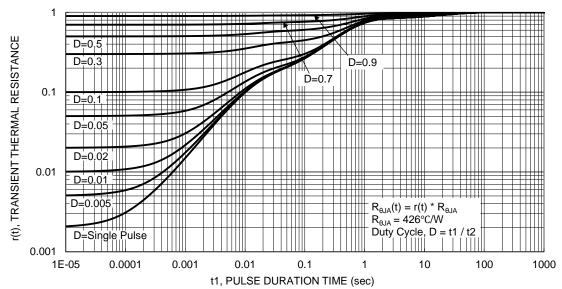


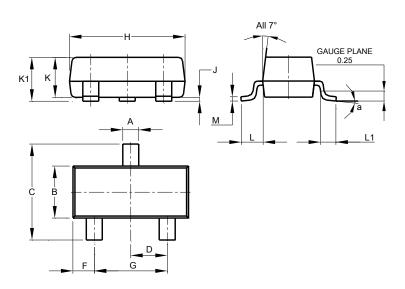
Figure 12. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

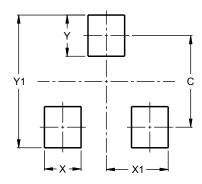


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Η	2.80	3.00	2.90				
7	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



Dimensions	Value (in mm)				
С	2.0				
X	0.8				
X1	1.35				
Y	0.9				
V1	2.0				



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